

Description

The ZXMN10A07F uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOT-23

General Features

 V_{DS} = 100V I_D =3 A

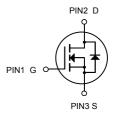
 $R_{DS(ON)}$ < 248m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
ZXMN10A07F	SOT-23	HXY MOSFET	3000

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Symbol Parameter		Units
VDS	Drain-Source Voltage	100	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	3	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	1	
Ідм	Pulsed Drain Current ²	5	А
PD@Ta=25°C	Total Power Dissipation ³	1	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R _θ JA	Thermal Resistance Junction-ambient ¹	125	°C/W
Rejc	Thermal Resistance Junction-Case ¹	80	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
△BVbss/△TJ	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.067		V/°C
	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =1A		210	248	
RDS(ON)		V _{GS} =4.5V , I _D =0.5A		244	290	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
$\Delta V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-4.2		mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			5	uA
Igss	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =1A		2.4		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.8	5.6	
Qg	Total Gate Charge (10V)			9.7	13.6	
Qgs	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =1A		1.6	2.2	nC
Q_{gd}	Gate-Drain Charge			1.7	2.4	
Td(on)	Turn-On Delay Time			1.6	3.2	
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V ,		19	34	
T _{d(off)}	Turn-Off Delay Time	R _G =3.3 I _D =1A		13.6	27	ns
T _f	Fall Time			19	38	
Ciss	Input Capacitance			508	711	
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		29	41	pF
Crss	Reverse Transfer Capacitance			16.4	23	
Is	Continuous Source Current ^{1,4}				1.2	Α
Іѕм	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			5	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
trr	Reverse Recovery Time	IE-10 41/4t-1000/		14		nS
Qrr	Reverse Recovery Charge	IF=1A , dI/dt=100A/μs , TJ=25°C		9.3		nC

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$

^{3.} The power dissipation is limited by 150°C junction temperature

^{4 .}The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

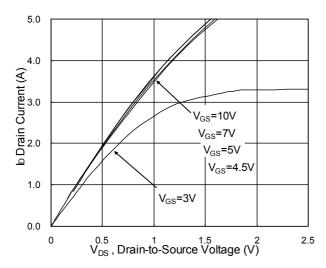


Fig.1 Typical Output Characteristics

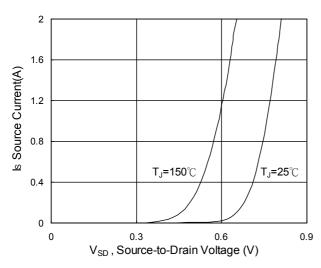


Fig.3 Forward Characteristics of Reverse

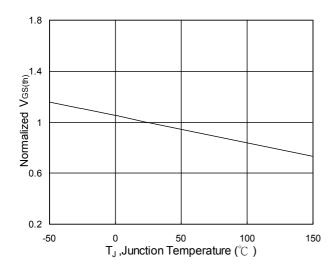


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

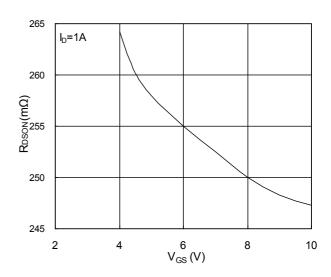


Fig.2 On-Resistance vs. Gate-Source

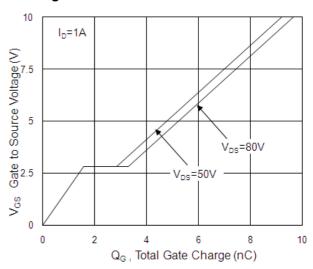


Fig.4 Gate-Charge Characteristics

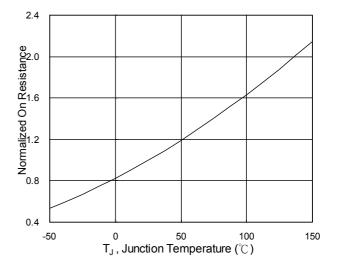
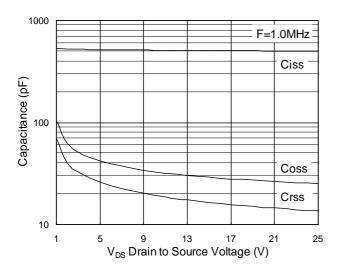


Fig.6 Normalized R_{DSON} vs. T_J





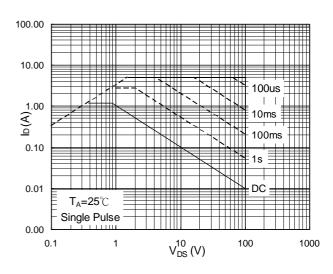


Fig.7 Capacitance

Fig.8 Safe Operating Area

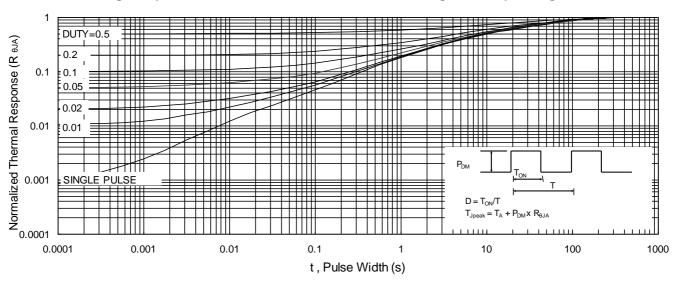
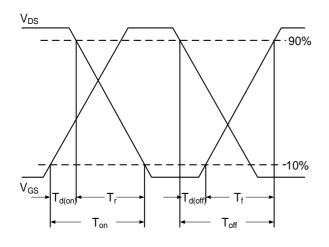


Fig.9 Normalized Maximum Transient Thermal Impedance



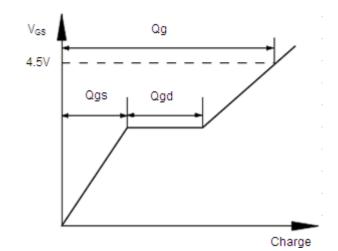
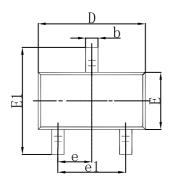


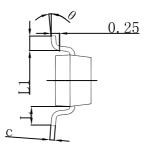
Fig.10 Switching Time Waveform

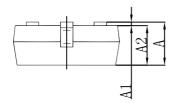
Fig.11 Gate Charge Waveform



SOT-23 Package Outline Dimensions

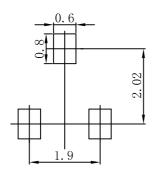






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550	REF	0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



- Note:
 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

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